D3343, OCTOBER 1989

- Extremely Low Offset Voltage ... 5 μV Max
- Extremely Low Change in Offset Voltage with Temperature ... 0.003 μV/°C Typ
- Low Input Offset Current ... 30 pA Max
- A_{VD} . . . 120 dB Min
- CMRR and k_{SVR} ... 110 dB Min
- Single-Supply Operation
- Common-Mode Input Voltage Range Includes the Negative Rail
- No Noise Degradation with External Capacitors Connected to V_{DD}_

description

The ICL7652 is a precision chopper-stabilized operational amplifier manufactured using Texas Instruments Advanced LinCMOS[™] process. This process, in conjunction with unique chopper-stabilization circuitry, produces an operational amplifier whose performance matches or exceeds that of similar devices available today.

Chopper stabilization techniques make possible extremely high dc precision by continuously nulling input offset voltage even with variations in temperature, time, common-mode voltage, and supply voltage. Additionally, low-frequency noise voltage is significantly reduced. This precision, coupled with the extremely high input impedance of the CMOS input stage, makes the ICL7652 an ideal choice for low-level signal-processing applications such as strain gauges, thermocouples, and other transducer amplifiers.

The ICL7652 input common-mode range includes the negative rail, thereby providing superior performance in either single-supply or split-

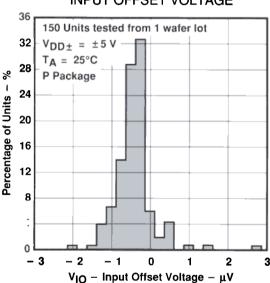
D, JG, OR P PACKAGE (TOP VIEW) C_{XA} 1 8 C_{XB}



AVAILABLE OPTIONS

		PACKAGE						
	VIO max		CERAMIC	PLASTIC				
TA	AT 25°C	OUTLINE	DIP	DIP				
		(D)	(JG)	(P)				
0°C to 70°C	5 μV	ICL7652D	ICL7652JG	ICL7652P				

D package is available taped and reeled. Add "R" suffix to device type (i.e., ICL7652DR).



DISTRIBUTION OF ICL7652 INPUT OFFSET VOLTAGE

supply applications, even at supply voltages as low as ± 1.9 V. The ICL7652 also features fast overload recovery time. Two external capacitors are required to operate the device; however, the on-chip chopper control circuitry is transparent to the user.

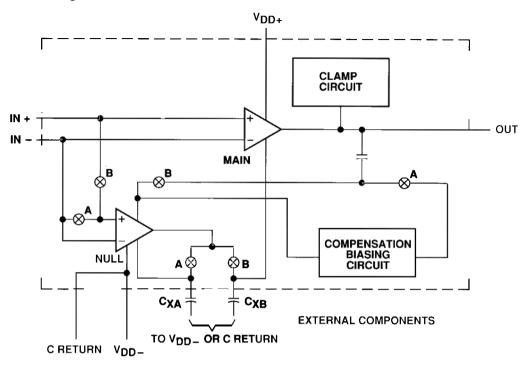
The device inputs and output are designed to withstand -100-mA surge currents without sustaining latchup. Additionally, the ICL7652 incorporates internal ESD protection circuits that prevent functional failures at voltages up to 2000 V as tested under MIL-STD-883C, Method 3015; however, care should be exercised in handling these devices, as exposure to ESD may result in degradation of the device parametric performance.

The ICL7652 is characterized for operation from 0°C to 70°C.

Advanced LinCMOS is a trademark of Texas Instruments Incorporated.



functional block diagram





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{DD+} (see Note 1) 8 V Supply voltage, V _{DD-} -8 V Differential input voltage (see Note 2) ±16 V Input voltage range, V _I (any input) ±8 V Input current, I _I (each input) ±5 mA Output current, I _O ±50 mA Duration of short-circuit current at (or below) 25°C (see Note 3) See Dissipation Rating Table Operating free-air temperature range, T _A 0°C to 70°C
· · ·
Storage temperature range –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D or P package 260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: JG package

NOTES: 1. All voltage values, except differential voltages, are with respect to the midpoint between V_{DD+} and V_{DD-}.

2. Differential voltages are at the noninverting input with respect to the inverting input.

3. The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.

DISSIPATION RATING TABLE

PACKAGE	T _A ≤ 25°C POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING
D	725 mW	5.8 mW/°C	464 mW
JG	1050 mW	8.4 mW/°C	672 mW
Р	1000 mW	8.0 mW/°C	640 mW

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V _{DD}	± 1.9	± 8	V
Common-mode input voltage, VIC	V _{DD} –	V _{DD +} - 1.9	V
Operating free-air temperature, TA	0	70	°C



electrical characteristics at specified free-air temperature, $V_{DD\pm} = \pm 5 V$ (unless otherwise noted)

	PARAMETER	TEST CONDITIONS		TA [†]	MIN	ТҮР	MAX	UNIT	
VIO	Input offset voltage			25°C		0.6	5		
10	input onset voltage		F	ull range			7.25	μV	
ανιο	Temperature coefficient of input offset voltage		F	ull range		0.003	0.05	μV/°C	
	Input offset voltage long-term drift (see Note 4)	$V_{IC} = 0$, $R_S = 50$	•• C	25°C		0.003	0.06	μV/mo	
Iю	Input offset current	+10 = 0, -15 = 0.	° • •	25°C		2	30	pA	
10			F	ull range			100		
IB	Input bias current			25°C		4	30	pА	
10			F	ull range		•	100		
	Common-mode input voltage range				- 5				
VICR		$R_S = 50 \Omega$	F	Full range	to			V	
					3.1				
VOM +	Maximum positive peak output voltage swing	$B_{I} = 10 k\Omega$		25°C	4.7	4.8		- v	
			F	ul range	4.7				
V _{OM} –	Maximum negative peak output voltage swing	RL = 10 kΩ		25°C	- 4.7	- 4.9		- v	
0111				ull range	- 4.7				
AVD	Large-signal differential voltage amplification	$V_{O} = \pm 4 V$, $R_{L} = 10$) kΩ –	25°C	120	150		dB	
		·0 _ · · · · L · · · · · ·		ull range	114				
fch	Internal chopping frequency			25°C		450		Hz	
CMRR	Common-mode rejection ratio	$V_{O} = 0$, $V_{IC} = V_{ICR}$		25°C	110	140		dB	
		$R_S = 50 \Omega$		ull range	104				
^k SVR	Supply-voltage rejection ratio ($\Delta V_{DD} \pm / \Delta V_{IO}$)	$V_{DD \pm} = \pm 1.9 \text{ V to } \pm 8 \text{ V}$		25°C	110	135		dB	
		$V_{\rm O} = 0, R_{\rm S} = 50$	0Ω F	ull range	104				
DD	Supply current	$V_{O} = 0$, No load	<u>``</u>	25°C		1.5	2.4	mA	
00			F	ull range			3.5		

NOTE 4: Typical values are based on the input offset voltage shift observed through 168 hours of operating life test at $T_A = 150^{\circ}$ C extrapolated to $T_A = 25^{\circ}$ C using the Arrhenius equation and assuming an activation energy of 0.96 eV.

operating characteristics at specified free-air temperature, $V_{DD\pm} = \pm 5 V$ (unless otherwise noted)

	DADAMETER							
	PARAMETER	TEST CONDITIONS	TAT	MIN	TYP	MAX	UNIT	
SR +	Positive slew rate at unity gain	$V_{O} = \pm 2.3 V_{0}$	25°C	2	2.8		V/µs	
011+	Tostive siew rate at unity gain	$R_{\rm I} = 10 \mathrm{k}\Omega,$	Full range	1.5			γ/μs	
SR - Neo	egative slew rate at unity gain	$C_{1} = 100 \text{pF}$	25°C	2.3	3.1		Mue	
UII	Negative slew rate at unity gain		Full range	1.8			V/µs	
vn	Equivalent input noise voltage (see Note 5)	f = 10 Hz	25°C		94			
۲n	Equivalent input hoise voitage (see hote 3)	f = 1 kHz	25°C		23		ייייך אייין	
VNUDD	Peak-to-peak equivalent input noise voltage	f = 0 to 1 Hz	25°C		0.8			
V _{N(PP)}	Teak-to-peak equivalent input noise voitage	f = 0 to 10 Hz	25°C		2.8		- μV	
I _n	Equivalent input noise current	f = 1 kHz	25°C		0.004		pA/√Hz	
	Gain-bandwidth product	$f = 10 \text{ kHz}, \text{R}_{L} = 10 \text{ k}\Omega,$ C ₁ = 100 pF	25°C		1.9		MHz	
<i>¢</i> m	Phase margin at unity gain	$R_{L} = 10 \text{ k}\Omega, C_{L} = 100 \text{ pF}$	25°C	_	48°			

[†]Full range is 0°C to 70°C.

NOTE 5: This parameter is tested on a sample basis for the ICL7652. For other test requirements, please contact the factory. This statement has no bearing on testing or nontesting of other parameters.

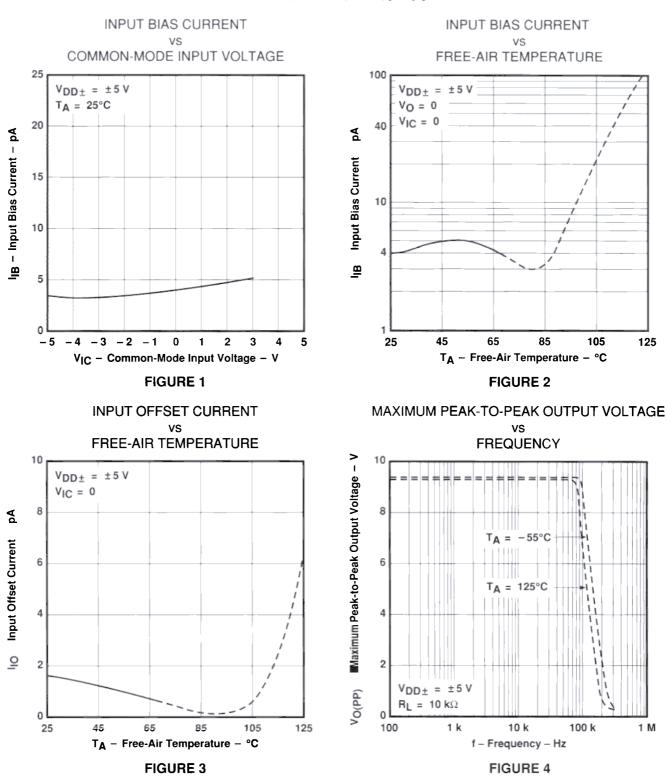


TYPICAL CHARACTERISTICS

table of graphs

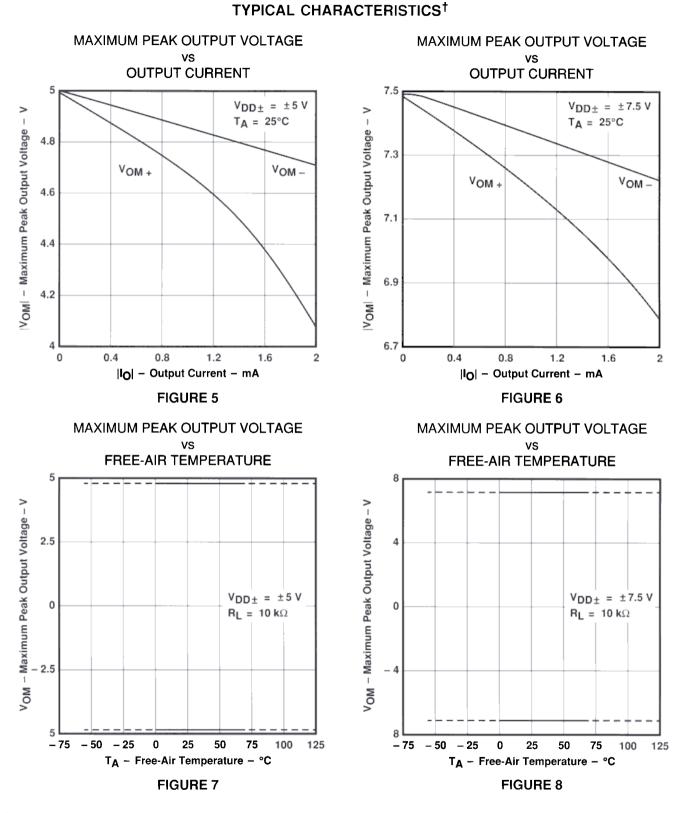
			FIGURE
lin	Input bias current	vs Common-mode input voltage	1
^I IВ	input bias current	vs Temperature	2
lio	Input offset current	vs Temperature	3
V _{O(PP)}	Maximum peak-to-peak output voltage swing	vs Frequency	4
	Maximum peak output voltage swing	vs Output current	5, 6
VOM	Maximum peak output voltage swing	vs Temperature	7, 8
A _{VD}	Differential voltage amplification	vs Frequency	9
~~0	Differential voltage amplification	vs Temperature	10
laa	Supply current	vs Supply voltage	11
^I DD	Supply current	vs Temperature	12
امم	Chart sizeuit eutrut eurrent	vs Supply voltage	13
los	Short-circuit output current	vs Temperature	14
SR	Slew rate	vs Supply voltage	15
30	Siew rate	vs Temperature	16
		Small-signal	17
	Pulse response	Large-signal	18
		vs Supply voltage	. 19
	Gain-bandwidth product	vs Temperature	20
v _n	Equivalent input noise voltage	vs Frequency	21
		vs Supply voltage	22
<i>¢</i> m	Phase margin	vs Temperature	23
	· · · · · · · · · · · · · · · · · · ·	vs Load capacitance	24
	Phase shift	vs Frequency	9



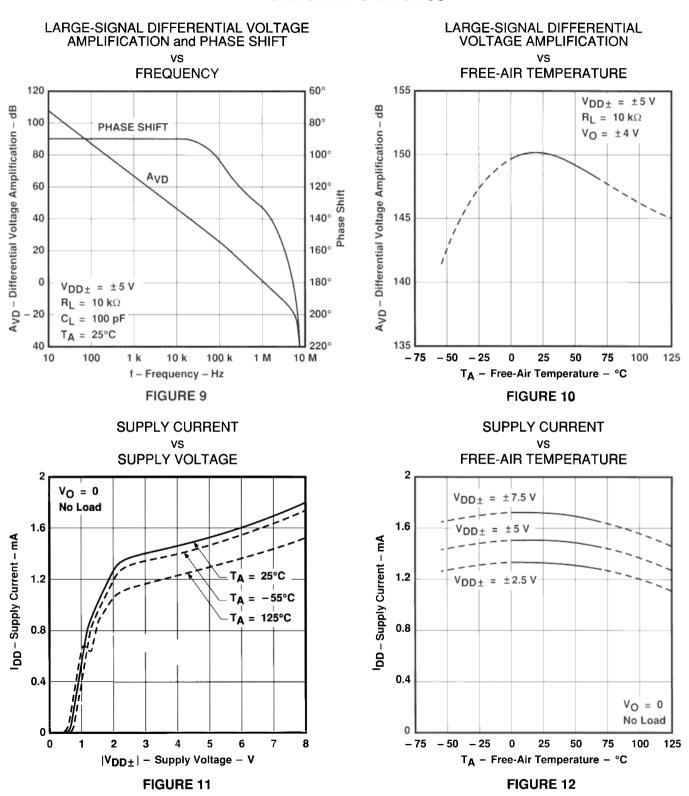


TYPICAL CHARACTERISTICS[†]



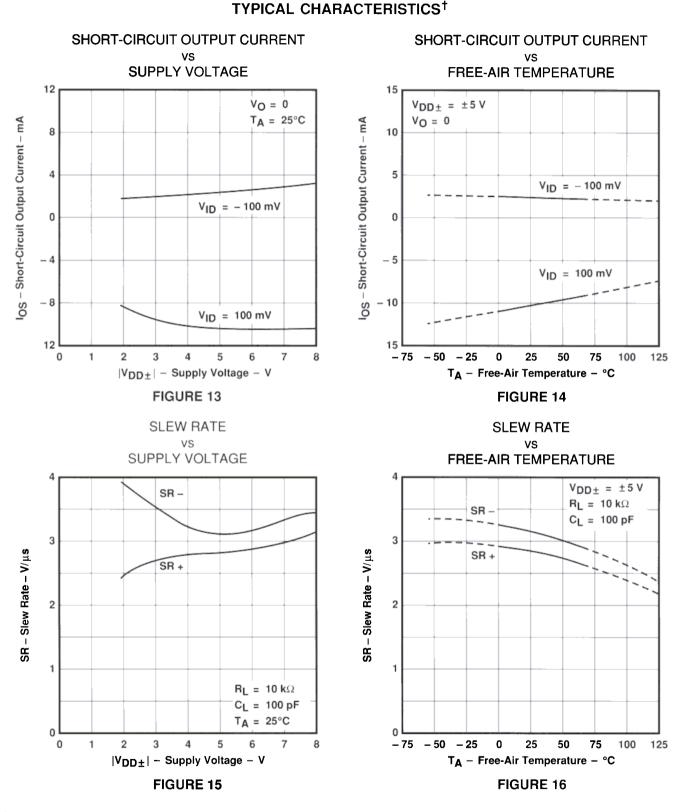




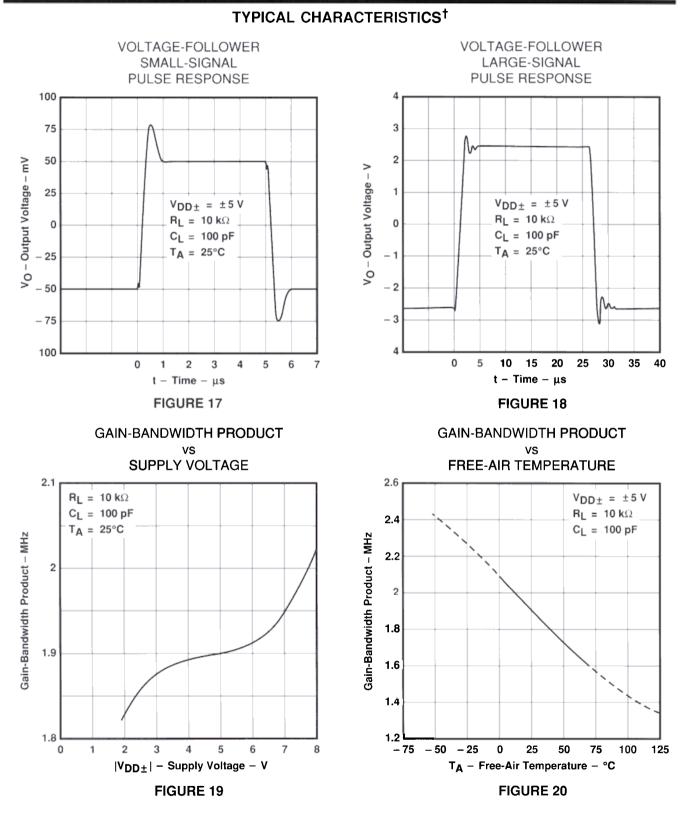


TYPICAL CHARACTERISTICS[†]

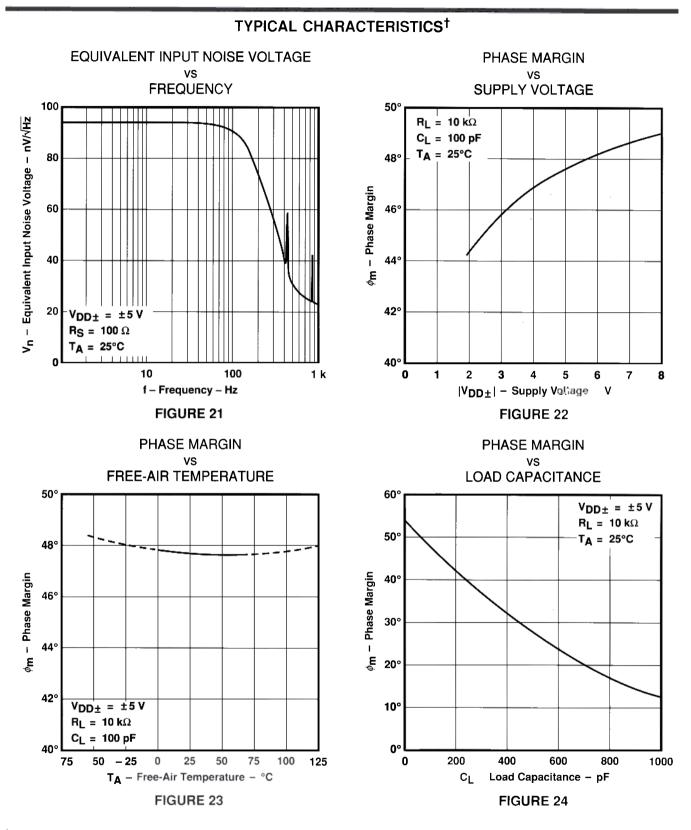












TYPICAL APPLICATION DATA

capacitor selection and placement

The two important factors to consider when selecting external capacitors C_{XA} and C_{XB} are leakage and dielectric absorption. Both factors can cause system degradation that negate the performance advantages realized by using the ICL7652.

Degradation from capacitor leakage becomes more apparent with increasing temperatures. Low-leakage capacitors and standoffs are recommended for operation at $T_A = 125$ °C. In addition, guardbands around the capacitor connections on both sides of the printed circuit board are recommended to alleviate problems caused by surface leakage on circuit boards.

Capacitors with high dielectric absorption tend to take several seconds to settle upon application of power, which directly affects input offset voltage. In applications needing fast settling of input offset voltage, it is recommended that high-quality film capacitors, such as mylar, polystyrene, or polypropylene, be used. In other applications, however, a ceramic or other low-grade capacitor may suffice.

Unlike many choppers available today, the ICL7652 is designed to function with values of C_{XA} and C_{XB} in the range of 0.1 μ F to 1 μ F without degradation to input offset voltage or input noise voltage. These capacitors should be located as close as possible to the C_{XA} and C_{XB} pins and returned to either the V_{DD-} pin or the C RETURN pin. Note that on many choppers, connecting these capacitors to the V_{DD-} pin causes degradation in noise performance, a problem that is eliminated on the ICL7652.

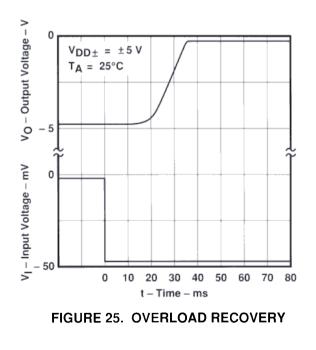
overload recovery/output clamp

When large differential input voltage conditions are applied to the ICL7652, the nulling loop attempts to prevent the output from saturating by driving C_{XA} and C_{XB} to internally-clamped voltage levels. Once the overdrive condition is removed, a period of time is required to allow the built-up charge to dissipate. This time period is defined as overload recovery time (see Figure 25). Typical overload recovery time for the ICL7652 is significantly faster than that of competitive products.

thermoelectric effects

To take advantage of the extremely low offset voltage temperature coefficient of the ICL7652, care must be taken to compensate for the thermoelectric effects present when two dissimilar metals are brought into contact with each other (such as device leads being soldered to a printed circuit board). It is not uncommon for dissimilar metal junctions to produce thermoelectric voltages in the range of several microvolts per degree Celsius (orders of magnitude greater than the 0.01- μ V/°C typical of the ICL7652).

To help minimize thermoelectric effects, careful attention should be paid to component selection and circuit board layout. Avoid the use of nonsoldered connections (such as sockets, relays, switches, etc.) in the input signal path. Cancel thermoelectric effects by duplicating the number of components and junctions in each device input. The use of low-thermoelectriccoefficient components, such as wire-wound resistors, is also beneficial.





TYPICAL APPLICATION DATA

avoiding latchup

The ICL7652 inputs and output are designed to withstand –100-mA surge currents without sustaining latchup. However, because CMOS devices are susceptible to latchup due to their inherent parasitic thyristors, techniques to reduce the chance of latchup should be used whenever possible. Internal protection diodes should not be forward biased in normal operation. Applied input and output voltages should not exceed the supply voltage by more than 300 mV. Care should be exercised when using capacitive coupling on pulse generators. Supply transients should be shunted by using decoupling capacitors (0.1 μ F typical) located across the supply rails as close to the device as possible.

The current path established if latchup occurs is usually between the supply rails and is limited only by the impedance of the power supply and the forward resistance of the parasitic thyristor. The chance of latchup occurring increases with increasing temperature and supply voltage.

electrostatic discharge protection

The ICL7652 incorporates internal ESD protection circuits that prevent functional failures at voltages at or below 2000 V. Care should be exercised in handling these devices, as exposure to ESD may result in degradation of the device parametric performance.

theory of operation

Chopper-stabilized operational amplifiers offer the best dc performance of any monolithic operational amplifier. This superior performance is the result of using two operational amplifiers – a main amplifier and a nulling amplifier – plus oscillator-controlled logic and two external capacitors to create a system that behaves as a single amplifier. With this approach, the ICL7652 achieves submicrovolt input offset voltage, submicrovolt noise voltage, and offset voltage variations with temperature in the $nV/^{\circ}C$ range.

The ICL7652 on-chip control logic produces two dominant clock phases – a nulling phase and an amplifying phase. The term "chopper-stabilized" derives from the process of switching between these two clock phases. Figure 26 shows a simplified block diagram of the ICL7652. Switches A and B are make-before-break types. During the nulling phase, switch A is closed, shorting the nulling amplifier inputs together and allowing the nulling amplifier to reduce its own input offset voltage by feeding its output signal back to an inverting input node. Simultaneously, external capacitor C_{XA} stores the nulling potential to allow the offset voltage of the amplifier to remain nulled during the amplifying phase.

During the amplifying phase, switch B is closed, connecting the output of the nulling amplifier to a noninverting input of the main amplifier. In this configuration, the input offset voltage of the main amplifier is nulled. Also, external capacitor C_{XB} stores the nulling potential to allow the offset voltage of the main amplifier to remain nulled during the next nulling phase.

This continuous chopping process allows offsetvoltage nulling during variations in time and temperature and over the common-mode input voltage range and power supply range. In addition, because the low-frequency signal path is through both the null and main amplifiers, extremely high gain is achieved.

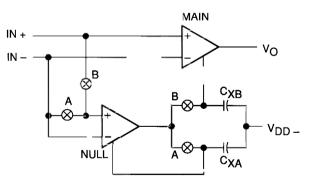


FIGURE 26. SIMPLIFIED BLOCK DIAGRAM

TYPICAL APPLICATION DATA

The low-frequency noise of a chopper amplifier depends on the magnitude of the component noise prior to chopping and the capability of the circuit to reduce this noise while chopping. The use of the Advanced LinCMOS[™] process, with its low-noise analog MOS transistors and patent-pending input stage design, significantly reduces the input noise voltage.

The primary source of nonideal operation in chopper-stabilized amplifiers is error charge from the switches. As charge imbalance accumulates on critical nodes, input offset voltage can increase, especially with increasing chopping frequency. This problem has been significantly reduced in the ICL7652 by use of a patent-pending compensation circuit and the Advanced LinCMOS[™] process.

The ICL7652 incorporates a feed-forward design that ensures continuous frequency response. Essentially, the gain magnitude of the nulling amplifier and compensation network crosses unity at the break frequency of the main amplifier. As a result, the high-frequency response of the system is the same as the frequency response of the main amplifier. This approach also ensures that the slewing characteristics remain the same during both the nulling and amplifying phases.

temperature coefficient of input offset voltage

Figure 27 shows the effects of package-induced thermal EMF. The ICL7652 can null only the offset voltage within its nulling loop. There are metal-to-metal junctions outside the nulling loop (bonding wires, solder joints, etc.) that produce EMF. In Figure 27, an ICL7652 was placed in an oven at 25°C at t = 0, biased up, and allowed to stabilize. At t = 3 min, the oven was turned on and allowed to rise in temperature to 125°C. As evidenced by the curve, the overall change in input offset voltage with temperature is much less than the specified maximum limit of 0.05 μ V/°C.

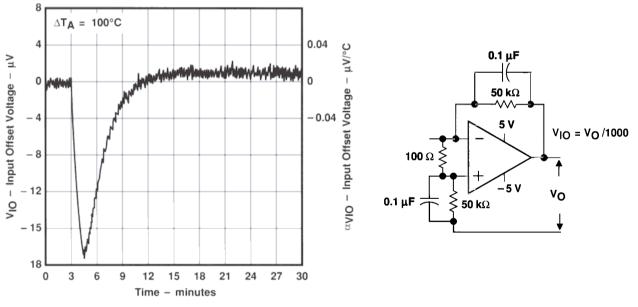


FIGURE 27. EFFECTS OF PACKAGE-INDUCED THERMAL EMF





PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
							(6)				
ICL7652P	LIFEBUY	PDIP	Р	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	ICL7652P	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽³⁾ MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Package Type Pins		L (mm)	W (mm)	Τ (μm)	B (mm)	
ICL7652P	Р	PDIP	8	50	506	13.97	11230	4.32	

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